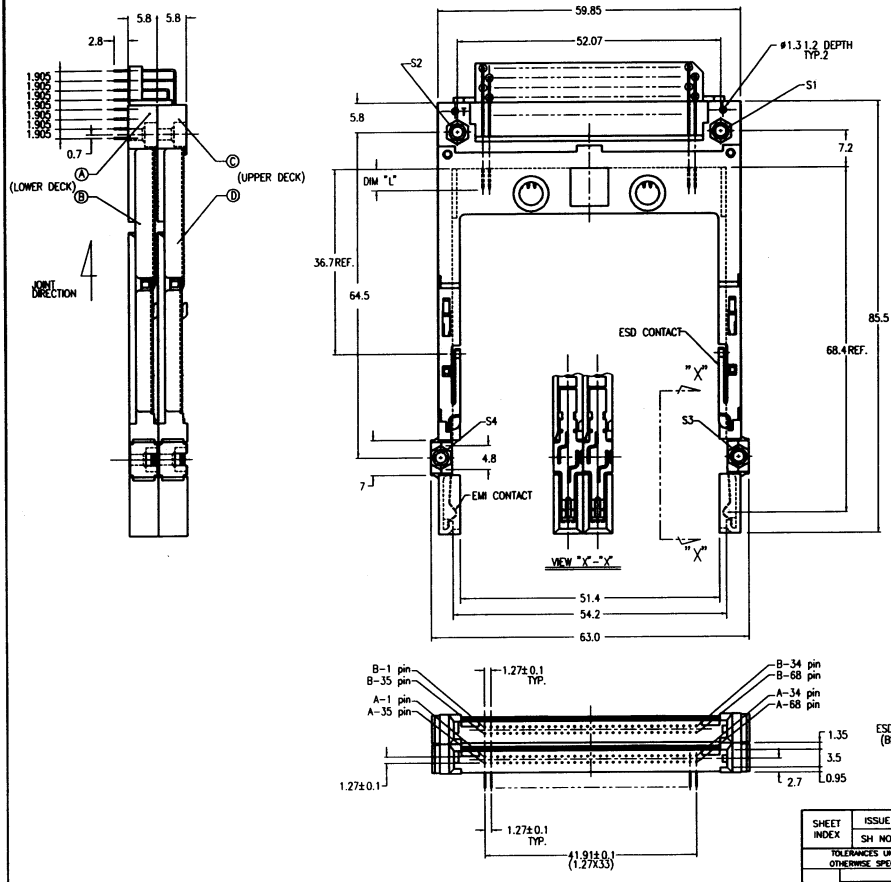


PRODUCT NO.
92790-000

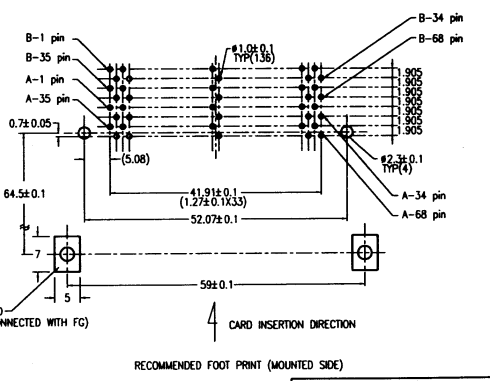
REVISIONS				
REV.	DESCRIPTION	ECN	BY	DATE
A	RELEASED			13/01/81 11/17/79
B	REVISED	150085	M.K.	07/79



NOTE

- ASSY PROCESS
 - TO MOUNT PART ①, ② ON PWB WITH SCREW (S1,S2) AND SOLDER.
 - TO JOINT PART ③ INTO PART ②, ④ THEN FIX PART ③, ④ WITH 2 SCREWS(S3,S4).
- MATERIAL
 - PART ①, ② (HEADER ASSY)
 PLASTIC : HOUSING LCP UL94V-0 BLACK
 LOCATOR G.F./S NYLON UL94V-0 BLACK
 PIN : PHOSPHOR BRONZE
 - PART ③, ④ (GUIDE ASSY)
 PLASTIC : GUIDE POLYPHTHARAMID UL94V-0 BLACK
 PLATE : STAINLESS
 EMI CONTACT : PHOSPHOR BRONZE
- FINISH(PIN)
 UNDER PLATING : 0.5 μm MIN. Ni
 CONTACT AREA : 0.1 μm MIN. Au OVER 0.5 m MIN. Pd-Ni
 SOLDER TAIL : 2.5 μm MIN. Sn-Pb
- DIM "L"

4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36.67	37.25
- GENERAL TOLERANCE : ±0.3
- SEE SHEET 1 REGARDING COMPONENTS.



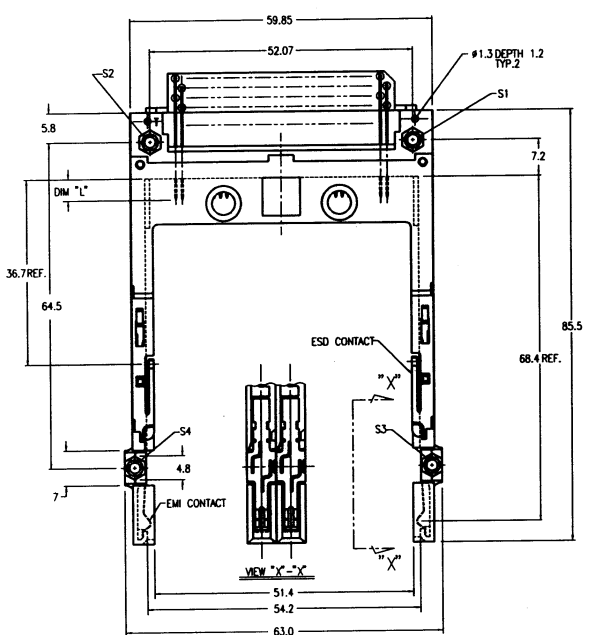
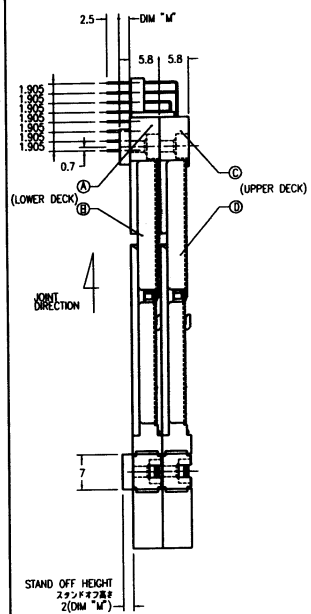
DO NOT SCALE. PRINT THIS INFORMATION IS CONFIDENTIAL AND IS OBLIGATED TO YOU ON CONDITION THAT NO FURTHER DISCLOSURE IS MADE BY YOU TO OTHER THAN BERG PERSONNEL, WITHOUT WRITTEN AUTHORIZATION FROM BERG ELECTRONICS JAPAN K.K.

SHEET INDEX	ISSUE	SH. NO.	DATE	CUSTOMER COPY	TITLE
			4/17/79		6SP DOUBLE LONG HEADER FOR TYPE 1/ II / III (WITH EMI CLIP)
	SEE NOTE ②				
	SEE NOTE ③				



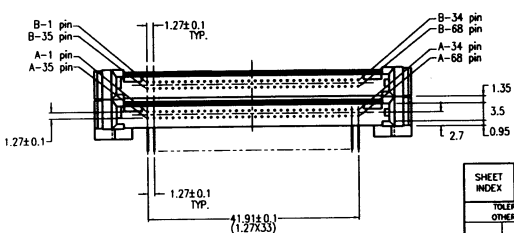
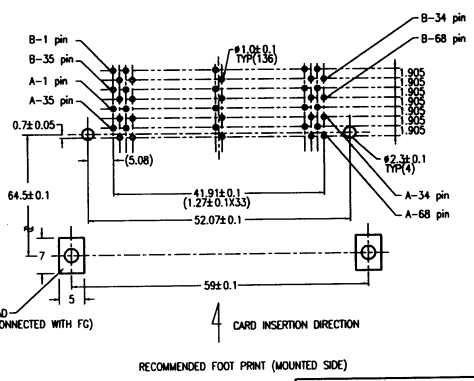
REVISIONS				
REV	DESCRIPTION	ECN	BY	DATE
A	RELEASED	130018	NJ	1/17/93
B	REVISED	150085	MJK	4/17/93

PRODUCT NO.
92790-020



- NOTE
- ASSY PROCESS
 - TO MOUNT PART ①, ②, ③ ON PWB WITH SCREW (S1,S2) AND SOLDER.
 - TO JOINT PART ④, ⑤ INTO PART ②, ③ THEN FIX PART ⑥, ⑦ WITH 2 SCREWS(S3,S4).
 - MATERIAL
 - PART ①, ② (HEADER ASSY)
 PLASTIC : HOUSING LCP UL94V-0 BLACK
 LOCATOR : C1/S/B NYLON UL94V-0 BLACK
 PIN : PHOSPHOR BRONZE
 - PART ③, ④ (GUIDE ASSY)
 PLASTIC : GUIDE POLY(PTHT)ARIMID UL94V-0 BLACK
 PLATE : STAINLESS
 EMI CONTACT : PHOSPHOR BRONZE
 - FINISH(PIN)
 UNDER PLATING : 0.5 μm MIN. Ni
 CONTACT AREA : 0.1 μm MIN. Au OVER 0.5 μm MIN. Pd-Ni
 SOLDER TAIL : 2.5 μm MIN. Sn-Pb
 - DM "L"

4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36.67	36.5mm
 - GENERAL TOLERANCE : ±0.3
 - SEE SHEET 1 REGARDING COMPONENTS.



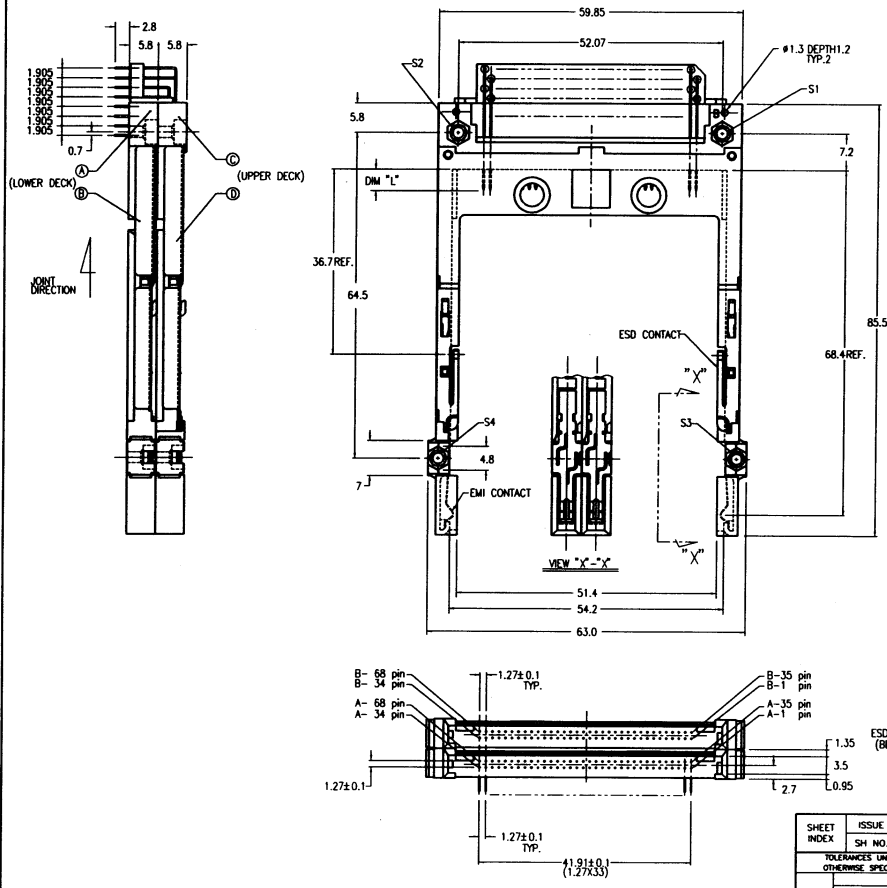
SHEET INDEX	ISSUE	SH. NO.	DATE	CUSTOMER COPY	SCALE	SIZE	DRWG. NO.	REV	SHEET
	SEE NOTE ①		4/17/93		2/1	C	92790	B	3of

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TITLE: 68P DOUBLE LONG HEADER FOR TYPE I / II / III (WITH EMI CLIP)

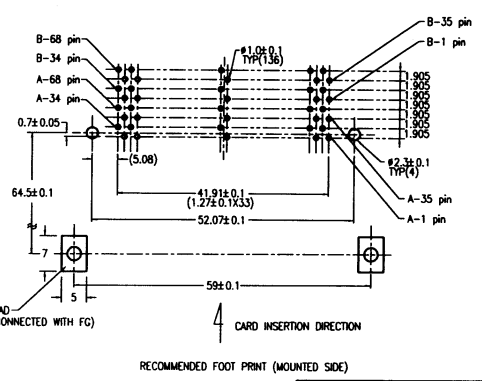
PRODUCT NO.
92790-500

REVISIONS			
REV	DESCRIPTION	ECN	BY DATE
A	RELEASED		US0018/NT 1/19/79
B	REVISED		US0008/MLK 4/27/79



- NOTE
- ASSY PROCESS
 - TO MOUNT PART ①, ② ON PWB WITH SCREW (S1,S2) AND SOLDER.
 - TO JOINT PART ③, ④ INTO PART ①, ② THEN FIX PART ⑤, ⑥ WITH 2 SCREWS(S3,S4).
 - MATERIAL
 - PART ①, ② (HEADER ASSY)
 - PLASTIC : HOUSING LCP UL94V-0 NATURAL
 - LOCATOR : G.F.6/8 NYLON UL94V-0 BLACK
 - PIN : PHOSPHOR BRONZE
 - PART ③, ④ (GUIDE ASSY)
 - PLASTIC : GUIDE POLYPHTHARAMID UL94V-0 BLACK
 - PLATE : STAINLESS
 - EMI CONTACT : PHOSPHOR BRONZE
 - FINISH(PIN)
 - UNDER PLATING : 0.5 μm MIN. Ni
 - CONTACT AREA : 0.1 μm MIN. Au OVER 0.5 μm MIN. Pd-Ni
 - SOLDER TAIL : 2.5 μm MIN. Sn-Pb
 - DIM "L"

4.25±0.1	3.5±0.1	5.0±0.1
OTHERS	36.67	33.5
 - GENERAL TOLERANCE : ±0.3
 - SEE SHEET 1 REGARDING COMPONENTS.



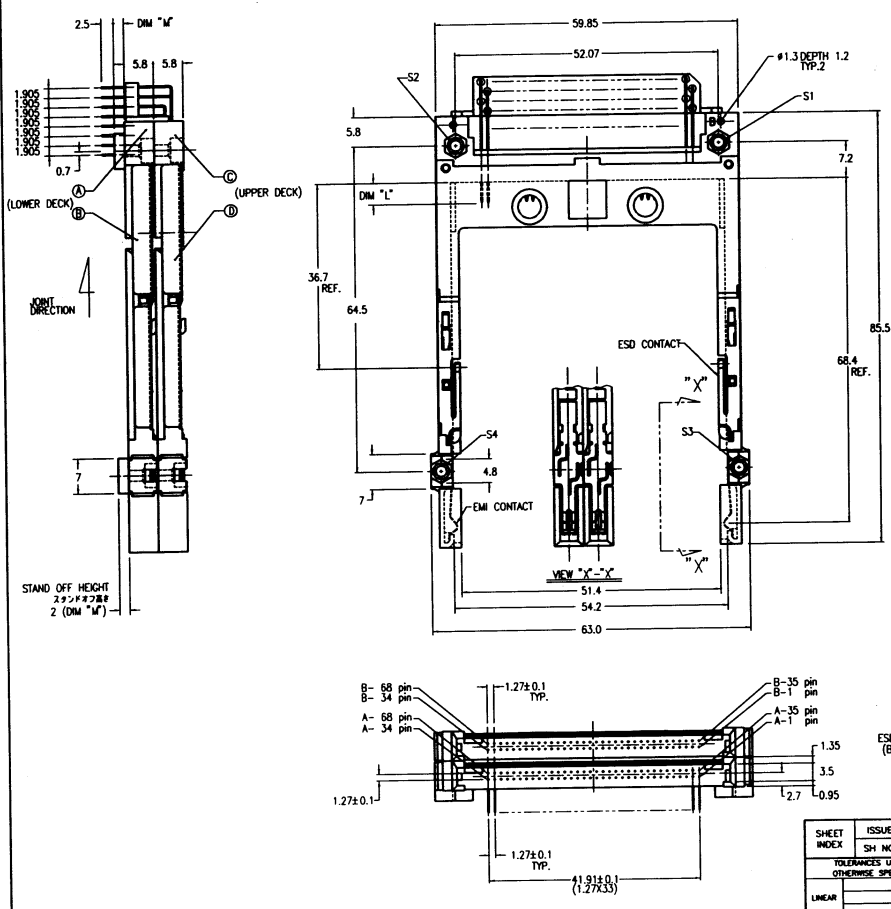
07-0034 REV. C
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SHEET INDEX	ISSUE	SH NO.	DATE	BY	CHKD	APPV	CUSTOMER COPY	TITLE
								68P DOUBLE LONG HEADER FOR TYPE I / II / III (WITH EMI CLIP)
								SCALE SIZE (DWG. NO.) 2/1 C 92790 B 4 of 4

BERG ELECTRONICS

REVISIONS			
REV	DESCRIPTION	ECN	BY DATE
A	RELEASED	130018	N.T. 1/29/79
B	REVISED	150085M.K.	4/27/79

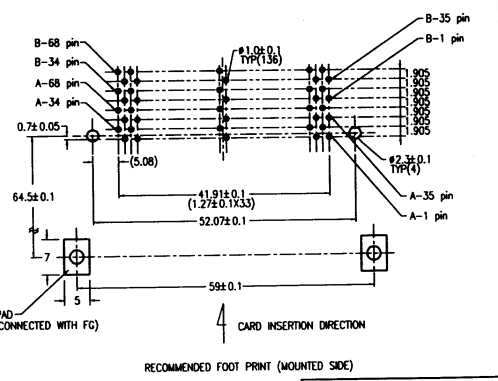
PRODUCT NO.
92790-520



NOTE

- ASSY PROCESS
 - TO MOUNT PART ②, ③ ON PWB WITH SCREW (S1,S2) AND SOLDER.
 - TO JOINT PART ②, ③ INTO PART ①, ④ THEN FIX PART ②, ③ WITH 2 SCREWS(S3,S4).
- MATERIAL
 - PART ①, ④ (HEADER ASSY)
 PLASTIC : HOUSING LCP UL94V-0 NATURAL
 : LOCATOR G.F.6/8 NYLON UL94V-0 BLACK
 PIN : PHOSPHOR BRONZE
 - PART ②, ③ (GUIDE ASSY)
 PLASTIC : GUIDE POLYPHTHAMID UL94V-0 BLACK
 PLATE : STAINLESS
 EMI CONTACT : PHOSPHOR BRONZE
- FINISH(PIN)
 - UNDER PLATING : 0.5 μm MIN. Ni
 - CONTACT AREA : 0.1 μm MIN. Au OVER 0.5 μm MIN. Pd-Ni
 - SOLDER TAIL : 2.5 μm MIN. Sn-Pb
- DIM "L"

4.25±0.1	3.58±0.1	5.0±0.1
OTHERS	36.67	36.67
- GENERAL TOLERANCE : ±0.3
- SEE SHEET 1 REGARDING COMPONENTS.



SHEET INDEX	ISSUE	SH NO.	DATE	CUSTOMER COPY	TITLE	SCALE	SIZE	UNIC. NO.	REV SHEET
	TOLERANCES UNLESS OTHERWISE SPECIFIED				68P DOUBLE LONG HEADER FOR TYPE I/II/III (WITH EMI CLIP)			92790	B 5 of
LINEAR	SEE NOTE ①		4/17/79			2/1	C		
	SEE NOTE ②								

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